

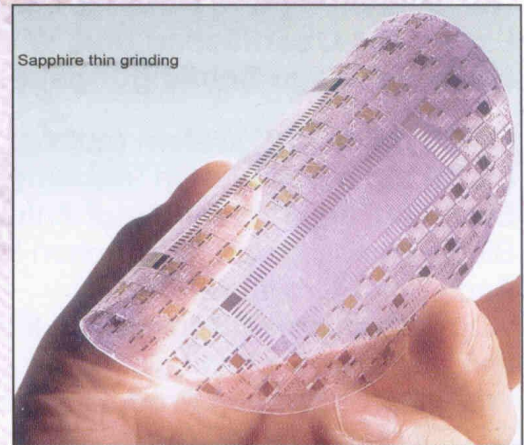
Ultrathin and thin Silicon Wafers

Ultraprecise Thinning to Target Thickness: $> 30 \mu\text{m}$



Advantages / Our Offer

- Grinding only (no polishing), dry etching (destressed)
- Excellent surfaces and TTV
- Extremely small damage depths
- To $70 \mu\text{m}$ at 12" wafers (also thinner on request)
- To $60 \mu\text{m}$ at 8" wafers (also thinner on request)
- To $50 \mu\text{m}$ at 6" wafers (also thinner on request)
- Single handling of ultrathin wafers
- Also solar orbital wafers
- We work on machines with advanced world standard and highest technology level
- We have experienced production managers
- SECON highspeed dry etching



Applications

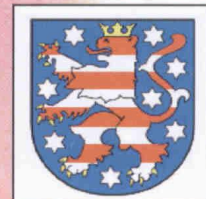
We grind on G&N NANOgrinder

Our products are mainly used for

- SOI - preparation
- SOI thinning: 8" to $15 \mu\text{m}$ ultra precise
- MEMS
- RFID
- Stacked Wafers
- Bumped Wafers
- Bonded Wafers



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Ultrathin Wafers/Chips - Diamond-Multi-Micro-Wire-Saw
Sales of Machines and Clusters - Development of Technologies - Job-Shop
Silicon, Sapphire, Glass, Quartz, Magnets, Other Brittle Crystals and Materials